

## Dual N-Channel 25-V (D-S) MOSFET

### PRODUCT SUMMARY

$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A) <sup>a</sup>	$Q_g$ (Typ.)
25	0.023 at $V_{GS} = 10$ V	8	5.5 nC
	0.028 at $V_{GS} = 4.5$ V	8	

### FEATURES

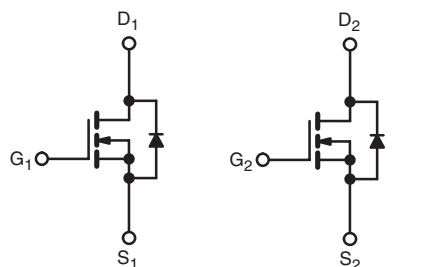
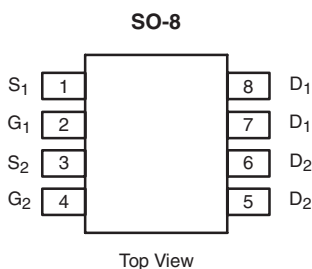
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**  
Available

### APPLICATIONS

- DC/DC Converter
- Gaming
- Notebook System Power



N-Channel MOSFET

N-Channel MOSFET

**Ordering Information:** Si4952DY-T1-E3 (Lead (Pb)-free)  
Si4952DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

### ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	25	V
Gate-Source Voltage	$V_{GS}$	$\pm 16$	
Continuous Drain Current ( $T_J = 150$ °C)	$T_C = 25$ °C	8 <sup>a</sup>	A
	$T_C = 70$ °C	7	
	$T_A = 25$ °C	7 <sup>b, c</sup>	
	$T_A = 70$ °C	5.6 <sup>b, c</sup>	
Pulsed Drain Current	$I_{DM}$	30	A
Continuous Source-Drain Diode Current	$T_C = 25$ °C	2.3	
	$T_A = 25$ °C	1.5 <sup>b, c</sup>	
Single Pulse Avalanche Current	$I_{AS}$	5	mJ
Single Pulse Avalanche Energy	$E_{AS}$	1.25	
Maximum Power Dissipation	$T_C = 25$ °C	2.8	W
	$T_C = 70$ °C	1.8	
	$T_A = 25$ °C	1.8 <sup>b, c</sup>	
	$T_A = 70$ °C	1.1 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to 150	°C

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	$R_{thJA}$	57	70	°C/W
Maximum Junction-to-Foot (Drain)	$R_{thJF}$	36	44	

Notes:

- Package Limited.
- Surface Mounted on 1" x 1" FR4 board.
- $t = 10$  s.
- Maximum under Steady State conditions is 110 °C/W.

**SPECIFICATIONS**  $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	25			V
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA		25		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	ΔV <sub>GS(th)</sub> /T <sub>J</sub>			- 4.7		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.0		2.2	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 16 V			± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 5 V, V <sub>GS</sub> = 10 V	20			A
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A		0.019	0.023	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 6.3 A		0.023	0.028	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 7 A		23		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 13 V, V <sub>GS</sub> = 0 V, f = 1 MHz		680		pF
Output Capacitance	C <sub>oss</sub>			120		
Reverse Transfer Capacitance	C <sub>rss</sub>			55		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 13 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 7 A		12	18	nC
		V <sub>DS</sub> = 13 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 7 A		5.5	8.5	
Gate-Source Charge	Q <sub>gs</sub>			2		
Gate-Drain Charge	Q <sub>gd</sub>			1.5		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		2.5		Ω
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 13 V, R <sub>L</sub> = 2.3 Ω I <sub>D</sub> ≅ 5.6 A, V <sub>GEN</sub> = 4.5 V, R <sub>g</sub> = 1 Ω		15	25	ns
Rise Time	t <sub>r</sub>			50	75	
Turn-Off Delay Time	t <sub>d(off)</sub>			20	30	
Fall Time	t <sub>f</sub>			10	15	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 13 V, R <sub>L</sub> = 2.3 Ω I <sub>D</sub> ≅ 5.6 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 1 Ω		10	15	
Rise Time	t <sub>r</sub>			12	20	
Turn-Off Delay Time	t <sub>d(off)</sub>			15	25	
Fall Time	t <sub>f</sub>			10	15	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.3	A
Pulse Diode Forward Current	I <sub>SM</sub>				30	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 5.6 A, V <sub>GS</sub> = 0 V		0.8	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 5.6 A, dI/dt = 100 A/μs, T <sub>J</sub> = 25 °C		15	30	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			8	16	nC
Reverse Recovery Fall Time	t <sub>a</sub>			8.5		ns
Reverse Recovery Rise Time	t <sub>b</sub>			6.5		

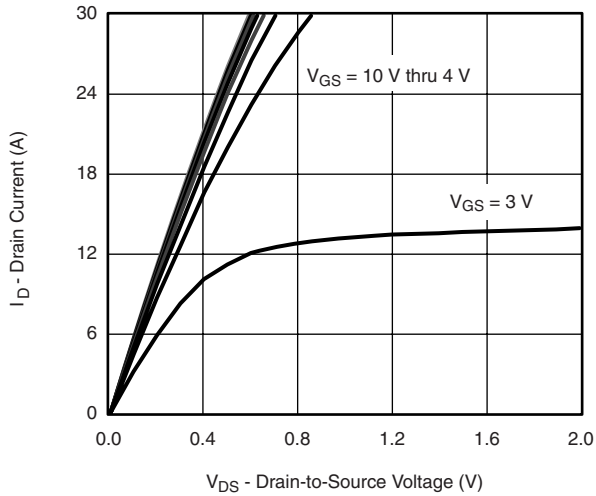
Notes:

a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

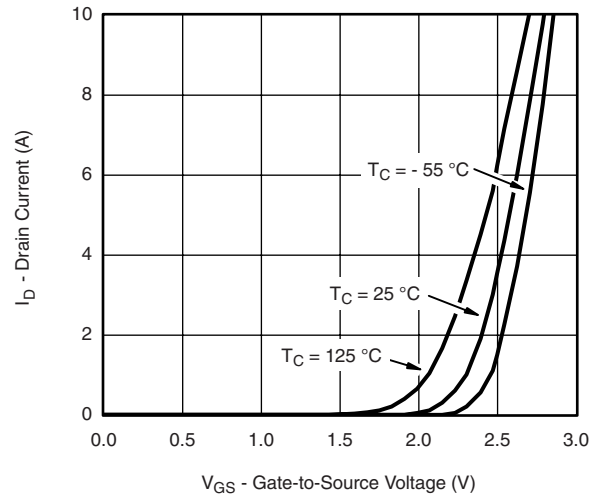
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

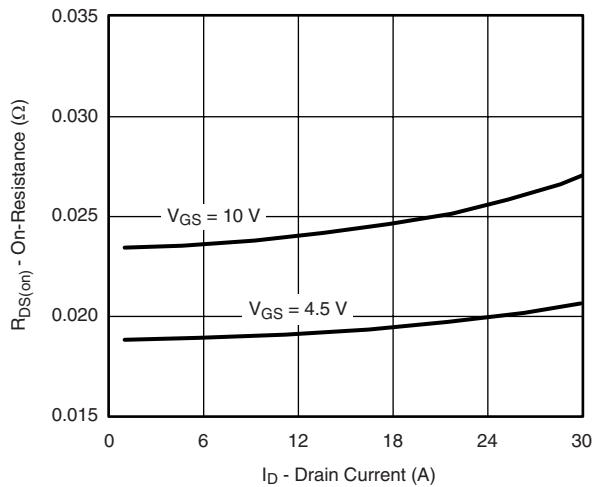
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



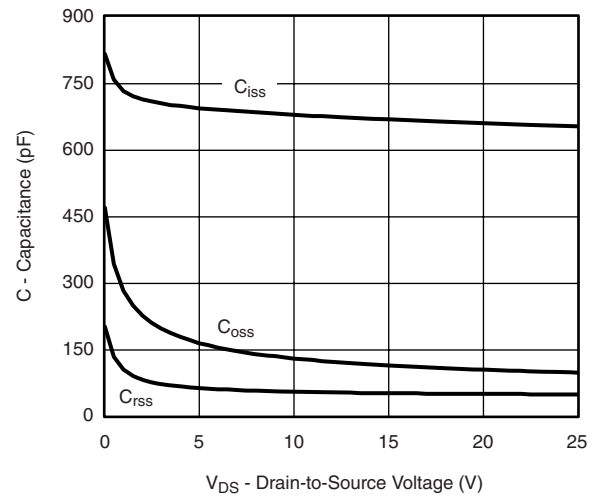
Output Characteristics



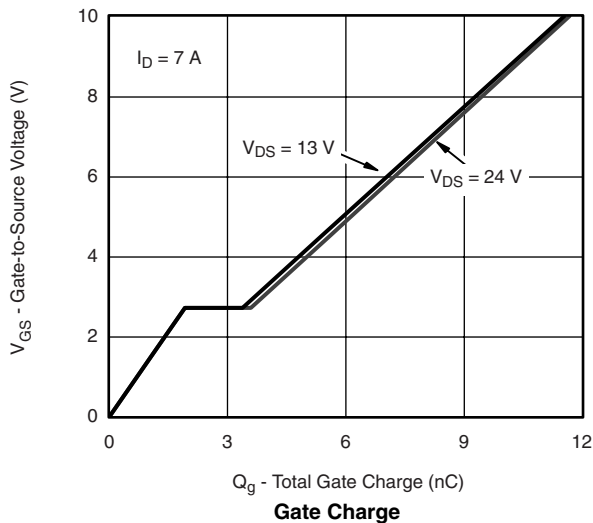
Transfer Characteristics



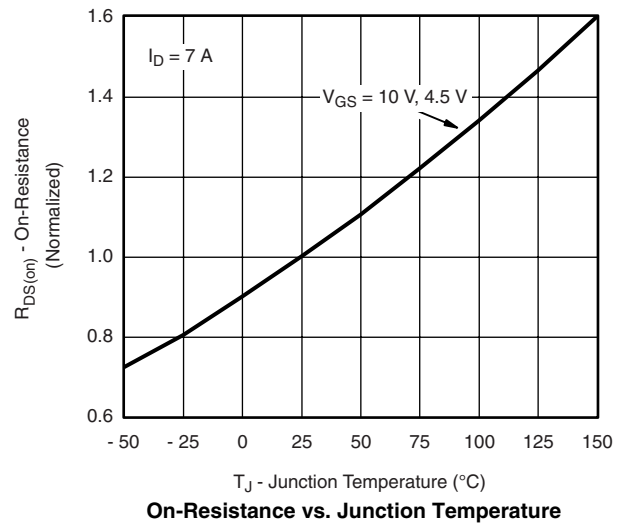
On-Resistance vs. Drain Current



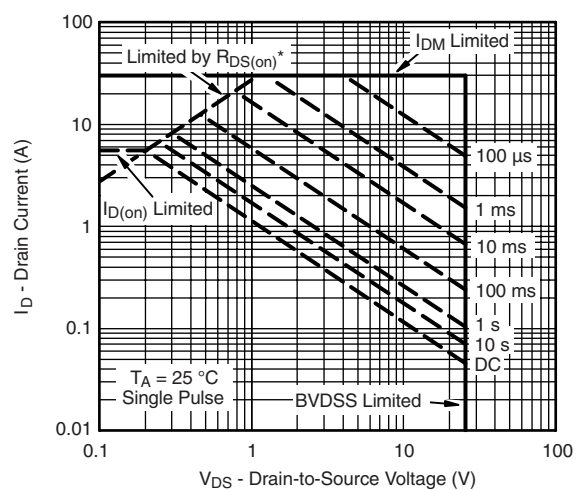
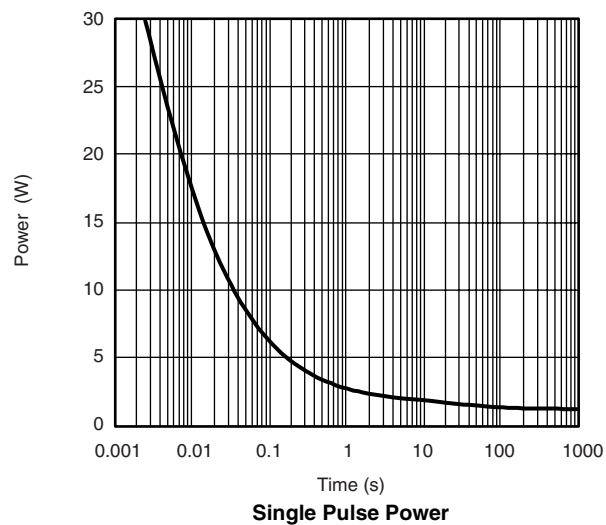
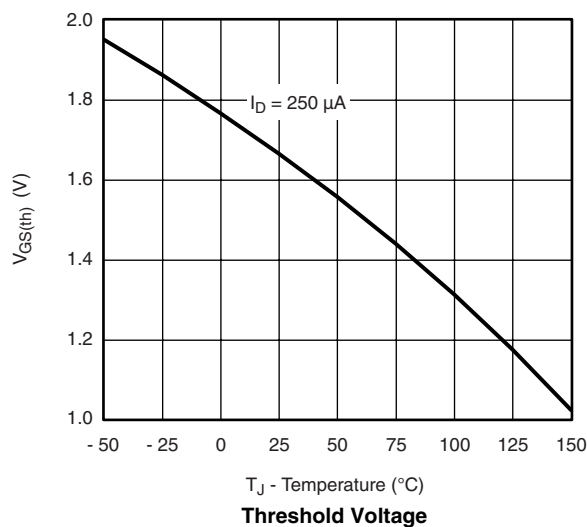
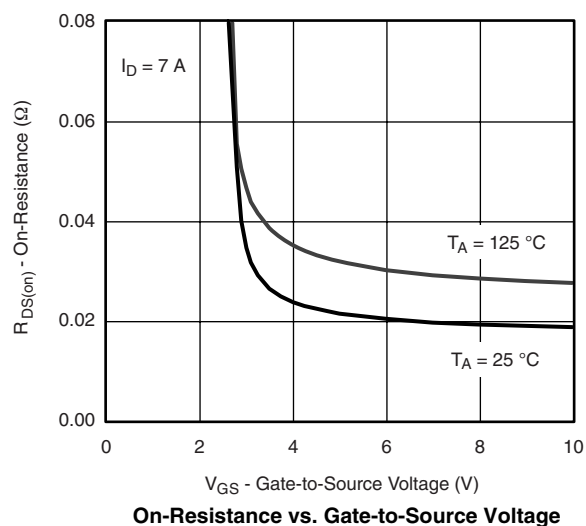
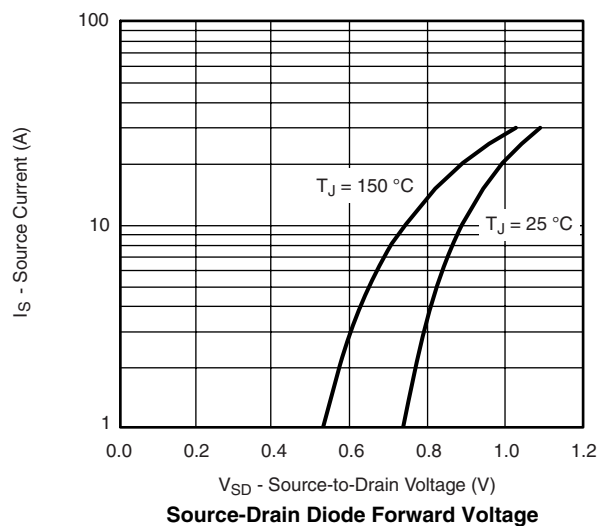
Capacitance



Gate Charge



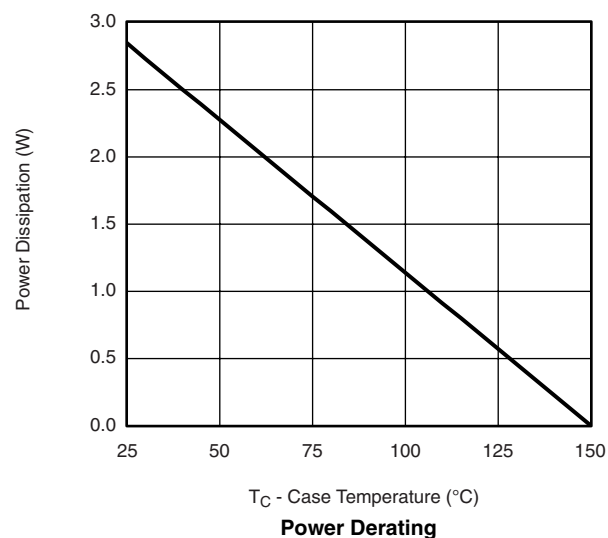
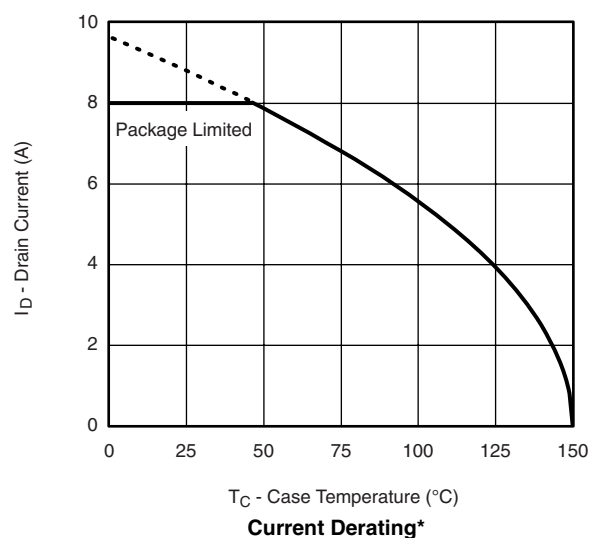
On-Resistance vs. Junction Temperature

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

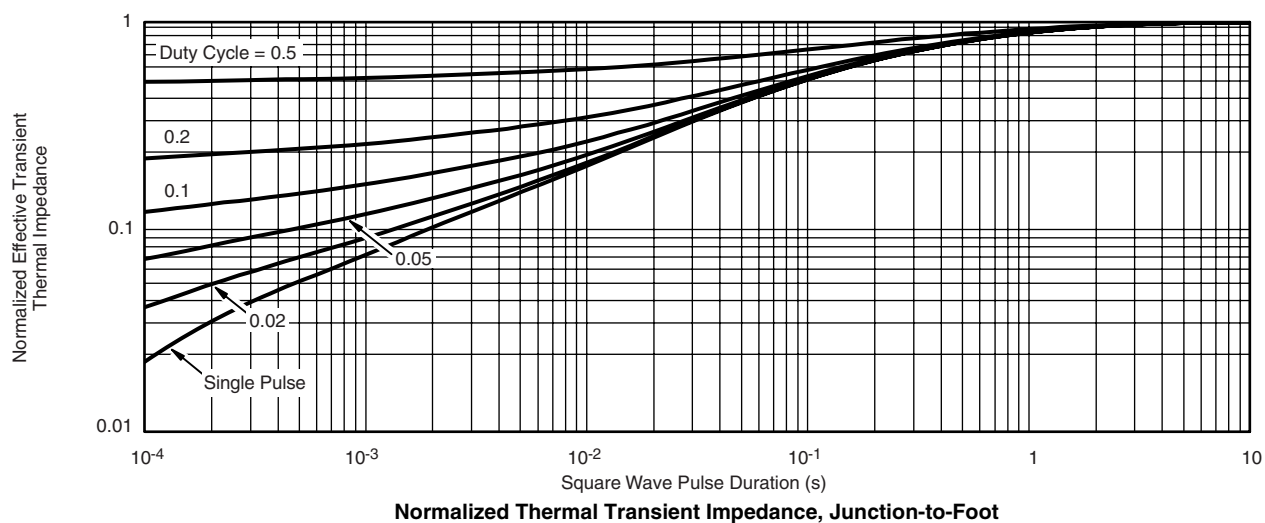
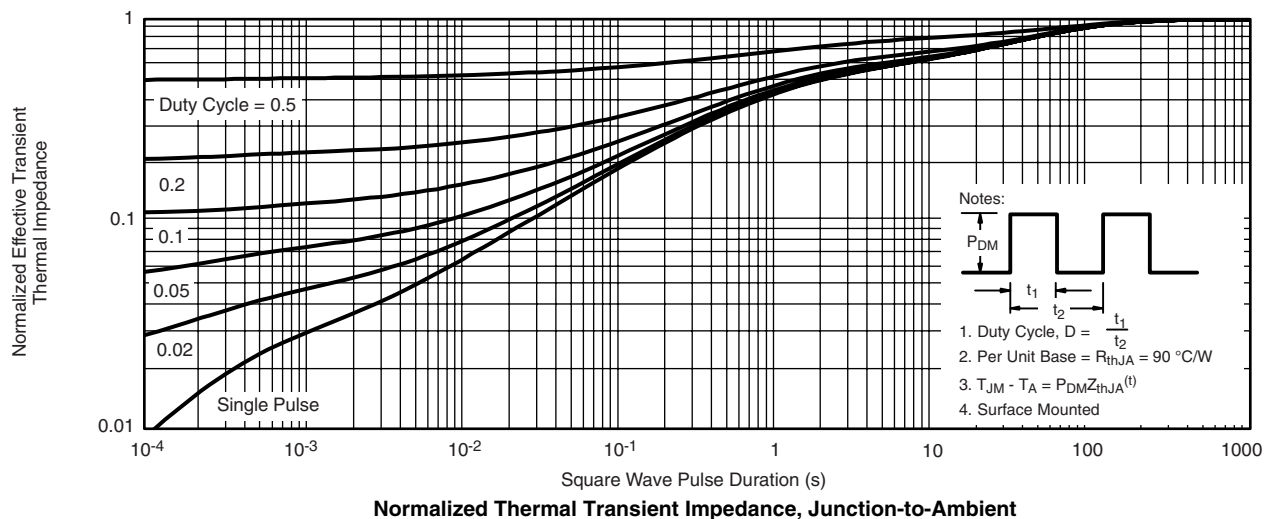
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

**Safe Operating Area, Junction-to-Ambient**

## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

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## SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012



DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A <sub>1</sub>	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°
S	0.44	0.64	0.018	0.026
ECN: C-06527-Rev. I, 11-Sep-06				
DWG: 5498				

## RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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